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A wireless communication device comprising:

a housing including an upper surface, a lower surface, and at least one side intermediate the upper surface and the lower surface and having a dimension less than smallest dimensions of the upper surface and the lower surface, and the at least one side surface having visibly perceptible indicia thereon; and

communication circuitry within the housing and the communication circuitry being configured to communicate wireless signals.

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The device according to claim

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wherein the housing comprises an encapsulant which contacts the communication circuitry.

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The device according to claim

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wherein the at least one side surface has a dimension less than about 100 mils.

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The device according to claim

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wherein the communication circuitry comprises radio frequency identification device circuitry.

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1. ~~58~~ ~~54~~ The device according to claim ~~57~~ wherein the communication
2. circuitry comprises radio frequency identification device circuitry.

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4. ~~59~~ ~~59~~ A wireless communication device comprising:
5. communication circuitry configured to communicate wireless signals;
6. and
7. an encapsulant configured to encapsulate and contact at least a
8. portion of the communication circuitry, wherein the encapsulant defines
9. at least one side surface and the at least one side surface has visibly
10. perceptible information thereon.

11. ~~60~~ ~~59~~
12. ~~60~~ ~~59~~ The device according to claim ~~62~~ wherein the encapsulant
13. has a thickness less than about 100 mils.

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15. ~~61~~ ~~59~~ The device according to claim ~~63~~ wherein the communication
16. circuitry comprises radio frequency identification device circuitry.

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~~61~~ ~~65~~ A radio frequency identification device comprising:

a housing including an upper surface and a lower surface which define a housing thickness of less than about 100 mils intermediate the lower surface and the upper surface, and the housing has visibly perceptible indicia thereon intermediate the upper surface and the lower surface; and

communication circuitry within the housing and configured to communicate wireless signals.

~~63~~ ~~66~~ The device according to claim ~~65~~ wherein the housing comprises an encapsulant which contacts at least portions of the support surface and the communication circuitry.

~~64~~ ~~67~~ The device according to claim ~~66~~ further comprising an antenna within the housing and coupled with the communication circuitry.

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1 A method of forming a wireless communication device
2 comprising:

3 providing communication circuitry configured to communicate
4 wireless signals;

5 providing a housing including an upper surface, a lower surface
6 and at least one side surface about the communication circuitry, the at
7 least one side surface has a dimension less than smallest dimensions of
8 the upper surface and the lower surface; and

9 providing visibly perceptible indicia on the at least one side
10 surface.

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12 ~~68~~ 70. The method according to claim ~~69~~ ⁶⁶ wherein the providing the
13 housing comprises encapsulating at least a portion of the communication
14 circuitry with an encapsulant.

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16 ~~68~~ 71. The method according to claim ~~70~~ ⁶⁷ wherein the encapsulating
17 comprises contacting at least the encapsulated portion of the
18 communication circuitry with the encapsulant.

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20 ~~69~~ 72. The method according to claim ~~69~~ ⁶⁶ wherein the at least one
21 side surface has a dimension less than about 100 mils.

1 ~~70~~ 73 The method according to claim ~~69~~ wherein the providing
2 communication circuitry comprises providing radio frequency identification
3 device circuitry.

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5 ~~71~~ 74 A method of forming a wireless communication device
6 comprising:

7 providing a substrate having a support surface defined by at least
8 one perimetral edge;

9 providing communication circuitry elevationally over the support
10 surface of the substrate and configured to communicate wireless signals;

11 encapsulating at least portions of the support surface of the
12 substrate and the communication circuitry using an encapsulant, the
13 encapsulant and the substrate respectively define an upper surface and
14 a lower surface and have a thickness less than a smallest dimension of
15 the at least one perimetral edge; and

16 providing visibly perceptible indicia on the encapsulant intermediate
17 the upper surface and the lower surface.

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19 ~~72~~ 75 The method according to claim ~~74~~ wherein the providing the
20 substrate comprises providing the substrate having a substantially
21 rectangular shape.

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~~73~~ ⁷¹ 76. The method according to claim ~~74~~ ⁷¹ wherein the encapsulating comprises contacting at least the encapsulated portions of the support surface of the substrate and, the communication circuitry with the encapsulant.

~~74~~ ⁷¹ 77. The method according to claim ~~74~~ ⁷¹ wherein the encapsulant and the substrate have a thickness less than about 100 mils.

~~75~~ ⁷¹ 78. The method according to claim ~~74~~ ⁷¹ wherein the providing communication circuitry comprises providing radio frequency identification device circuitry.

~~76~~ 79. A method of forming a wireless communication device comprising:

providing communication circuitry configured to communicate wireless signals;

encapsulating at least a portion of the communication circuitry with an encapsulant which contacts at least the encapsulated portion of the communication circuitry, the encapsulant forming at least one side surface; and

providing visibly perceptible indicia upon the at least one side surface of the encapsulant.

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~~78~~ 80. The method according to claim ~~79~~ wherein the at least one side surface of the encapsulant has a dimension less than about 100 mils.

~~78~~ 81. The method according to claim ~~79~~ wherein the providing communication circuitry comprises providing radio frequency identification device circuitry.

~~79~~ 82. A method of forming a radio frequency identification device comprising:

providing radio frequency identification device circuitry configured to communicate wireless signals;

providing a housing including an upper surface, a lower surface, and at least one side surface about the communication circuitry, the at least one side surface having a dimension less than about 100 mils; and

providing visibly perceptible indicia on the at least one side surface.

~~80~~ 83. The method according to claim ~~82~~ wherein the providing the housing comprises providing an encapsulant over at least a portion of a support surface of a substrate.

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~~81~~ 84. The method according to claim ~~83~~ wherein the encapsulant contacts at least portions of the support surface and the radio frequency identification device circuitry.

~~82~~ 85. A method of forming a radio frequency identification device comprising:

providing radio frequency identification device circuitry configured to communicate wireless signals;

coupling a power source with the radio frequency identification device circuitry;

coupling an antenna with the radio frequency identification device circuitry;

providing a housing including an upper surface, a lower surface and at least one side surface about at least portions of the radio frequency identification device circuitry, the power source and the antenna, the at least one side surface having a dimension less than smallest dimensions of the upper surface and the lower surface; and

providing visibly perceptible indicia on the at least one side surface.